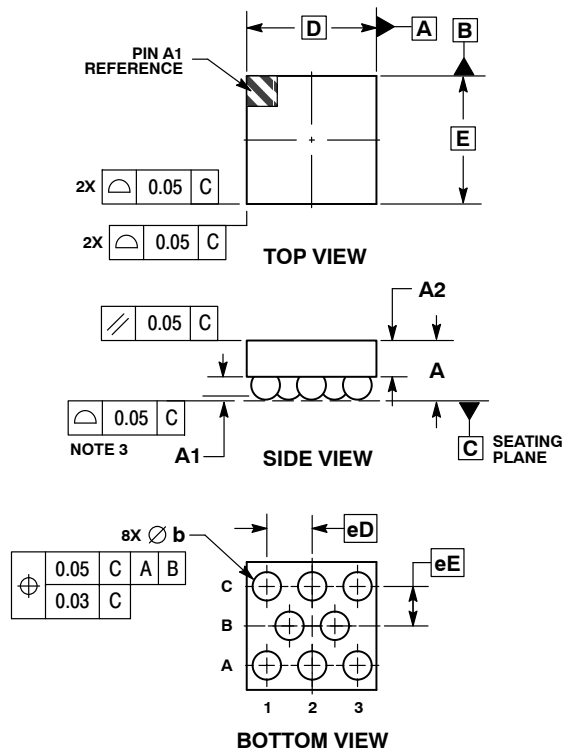




SCALE 4:1

WLCSP8, 1.43x1.41
CASE 567BE
ISSUE O

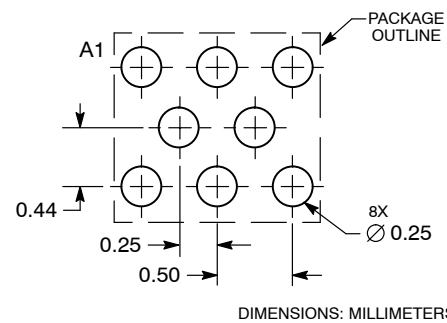
DATE 26 JUL 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40	REF
b	0.29	0.35
D	1.43	BSC
E	1.41	BSC
eD	0.50	BSC
eE	0.435	BSC

RECOMMENDED SOLDERING FOOTPRINT*


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP8, 1.43X1.41	PAGE 1 OF 1

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